



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-07-10
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	EU6S*UF97JC2	A	Z8GA	2017-07-10
Amount	UoM	Unit type	ST ECOPACK Grade	
54.50	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
ting is used or other bulk terminat	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	5X4.4X0.9	16	gull wing	
Comment	Package: 6S TSSOP 16 BODY 4.4 PITCH 0.65; MDF valid for ST26C32ABTR			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	EU65*UF97JC2						
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Die	Other inorganic materials	2.212	mg	supplier	die	Silicon (Si)	7440-21-3		2.133	mg	964286	39138	
				supplier	metallization	Aluminium (Al)	7429-90-5		0.018	mg	8137	330	
				supplier	Passivation	Silicon Nitride	12033-89-5		0.007	mg	3165	128	
				supplier	Passivation	Silicon Oxide	7631-86-9		0.030	mg	13562	550	
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.024	mg	10850	440	
Leadframe	Copper & its alloys	19.320	mg	supplier	alloy	Copper (Cu)	7440-50-8		18.244	mg	944306	334752	
				supplier	alloy	Nickel (Ni)	7440-02-0		0.609	mg	31522	11174	
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.031	mg	1605	569	
				supplier	alloy	Silicon (Si)	7440-21-3		0.135	mg	6988	2477	
				supplier	metallization	Silver (Ag)	7440-22-4		0.301	mg	15580	5523	
Die attach	Other Organic Materials	0.504	mg	supplier	glue	Silver(Ag)	7440-22-4		0.393	mg	779762	7211	
				supplier	glue	Acrylate monomer	Proprietary		0.091	mg	180556	1670	
				supplier	glue	Polybutadiene diacrylate	Proprietary		0.010	mg	19841	183	
				supplier	glue	Epoxy resin	25068-38-6		0.010	mg	19841	183	
Bonding wires	Precious metals	0.212	mg	supplier	wire	Gold (Au)	7440-57-5		0.212	mg	1000000	3890	
Encapsulation	Other Organic Materials	32.039	mg	supplier	mold compound	Amorphous silica	60676-86-0		27.109	mg	846125	497413	
				supplier	mold compound	Crystal silica	14808-60-7		0.950	mg	29651	17431	
				supplier	mold compound	Epoxy resin-1	Proprietary		0.573	mg	17884	10514	
				supplier	mold compound	Epoxy resin-2	25068-38-6		1.274	mg	39764	23376	
				supplier	mold compound	Phenol Resin	29690-82-2		0.064	mg	1998	1174	
Finishing	Other inorganic materials	0.213	mg	supplier	mold compound	Carbon Black	1333-86-4		2.069	mg	64578	37963	
				supplier	Connection coating	Tin (Sn)	7440-31-5		0.213	mg	1000000	3908	